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Amendments to the Specification

A “flip-connection” package having melted metal bumps for connection to another assembly, is shown in Fig. 2. The metal bumps **260** are formed on the bottom of the ceramic base **210**. The metal bumps are connected by the conductive pattern of the ceramic base and the flip-connections **230** to a semiconductor die **220**. The semiconductor device is enclosed by a frame **240** and cover **250**. Some methods for providing packages with flip connections are more fully described in United States Patents 5,627,406, 5,904,499 and the copending application, ~~entitled INTERCONNECTION METHODS~~ United States Patent 6,613,605, filed simultaneously with the current application, and which is incorporated herein by reference.